NPN Low Power, High Voltage Silicon Transistor

Features

- Available in JAN, JANTX and JANTXV per MIL-PRF-19500/368 •
- TO-39, TO-5, and UA Package Types
- Suitable For Drivers in High-Voltage Low Current Inverters, Switching and • Series Regulators

Electrical Characteristics ($T_A = +25^{\circ}C$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Units	Min.	Max.
Emitter - Base Cutoff Current	V _{EB} = 7.0 V dc	I _{EBO1}	µA dc	Ι	10
Collector - Emitter Cutoff	V _{CE} = 300 V dc 2N3439, L, UA V _{CE} = 200 V dc 2N3440, L, UA	I _{CEO}	µA dc		2 2
Collector - Emitter Cutoff Current	V _{BE} = -1.5 V dc V _{CE} = 450 V dc 2N3439, L, UA V _{CE} = 300 V dc 2N3440, L, UA	I _{CEX}	µA dc	_	5 5
Collector - Base Cutoff Current	V _{CB} = 360 V dc 2N3439, L, UA V _{CB} = 250 V dc 2N3440, L, UA	I _{CBO1}	µA dc	_	2 2
Collector - Base Cutoff Current	V _{CB} = 450 V dc 2N3439, L, UA V _{CB} = 300 V dc 2N3440, L, UA	I _{CBO2}	µA dc	_	5 5
Base - Emitter Voltage (saturated)	$I_{\rm C}$ = 50 mA dc, $I_{\rm B}$ = 4 mA dc	V _{BE(sat)}	V dc		1.3
Collector - Emitter Voltage (saturated)	$I_{\rm C}$ = 50 mA dc, $I_{\rm B}$ = 4 mA dc	V _{CE(sat)}	V dc		0.5
Forward Current Transfer Ratio	V_{CE} = 10 Vdc, I _C = 20 mA dc V_{CE} = 10 Vdc, I _C = 2 mA dc V_{CE} = 10 Vdc, I _C = 0.2 mA dc	h _{FE}	-	40 30 10	160
Collector - Emitter Cutoff Current	T _A = +150°C V _{CB} = 360 V dc 2N3439, L, UA V _{CB} = 250 V dc 2N3440, L, UA	І _{своз}	µA dc		6 6
Forward – Current Transfer Ratio	T _A = -55°C V _{CE} = 10 V dc, I _C = 20 mA dc	h _{FE4}		15	

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Electrical Characteristics

Parameter	Test Conditions	Symbol	Units	Min.	Max.
Dynamic Characteristics					
Magnitude of Common-Emitter Small Signal Short Circuit Forward-Current Transfer Ratio	V_{CE} = 10 V dc, I _C = 10 mA dc, f = 5 MHz	h _{FE}		3	15
Output Capacitance (Input Open Circuited)	V _{CB} = 10 V dc, I _E = 0, 100 kHz ≤ f ≤ 1 MHz	C _{obo}	pF	_	10
Small-Signal Short-Circuit Forward-Current Transfer Ratio	V_{CE} = 10 V dc, I _C = 5 mA dc, f = 1 kHz	h _{fe}		25	
Input Capacitance (Output Open Circuited)	V_{CB} = 5 V dc, I _E = 0, 100 kHz ≤ f ≤ 1 MHz	C _{ibo}	pF	—	75
Switching Characteristics	-				
Turn-On Time	V_{CC} = 200V dc, I _C = 20 mA dc, I _{B1} = 2 mA dc	t _{on}	μs	—	1.0
Turn-Off Time	V_{CC} = 200V dc, I _C = 20 mA dc, I _{B1} = -I _{B2} = 2 mA dc	t _{off}	μs	_	10

Absolute Maximum Ratings ($T_A = +25^{\circ}C$ unless otherwise specified)

Ratings		2N3439	2N3440	
Collector - Emitter Voltage	V _{CEO}	350 V dc	250 V dc	
Collector - Base Voltage	V _{CBO}	450 V dc	300 V dc	
Emitter - Base Voltage	V _{EBO}	7.0 V dc		
Collector Current	Ι _C	1.0 A dc		
Junction & Storage Temperature Range	T _J , T _{STG}	-65°C to +200°C		



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Absolute Maximum Ratings ($T_A = +25^{\circ}C$ unless otherwise specified)

Thermal Characteristics	Symbol	Max. Value
Thermal Resistance, Junction to Ambient 2N3439, 2N3439L 2N3439UA 2N3440, 2N3440L 2N3440UA	$R_{\theta JA}{}^{(3)}$	175°C/W
Thermal Resistance, Junction to Case 2N3439,2N3440 2N3439L, 2N3440L 2N3439UA, 2N3440UA	R _{θJC} ⁽³⁾	30°C/W N/A
Thermal Resistance, Junction to Solder Pad 2N3439UA, 2N3440UA	R _{ejsp} ⁽³⁾	70°C/W

(1) For thermal impedance curves see figures 10, 11, 12, and 13 of MIL-PRF-19500/368

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Absolute Maximum Ratings (T_A = +25°C unless otherwise specified)

Characteristics	Symbol	Max. Value
T _A = +25°C 2N3439, 2N3439L 2N3439UA, 2N3439U4 2N3440, 2N3440L 2N3440UA, 2N3440U4	P _T ⁽¹⁾	0.8 W
T _c = +25°C 2N3439,2N3440 2N3439L, 2N3440L 2N3439UA, 2N3440UA 2N3439U4, 2N3440U4	P _T ⁽²⁾	5.0 W N/A 5 W
T _{SP} = +25°C 2N3439UA, 2N3440UA	P _T ⁽²⁾	2.0 W

(1) For derating see figures 6 of MIL-PRF-19500/368

(2) For derating see figures 7, 8. and 9 of MIL-PRF-19500/368

DC Tests: $T_c = +25^{\circ}C$; I Cycle; t =1.0s Test 1: $V_{CE} = 5 V dc$; I _c = 1.0 A dc All types
Test 1: $V_{CE} = 5 V dc; I_C = 1.0 A dc$ All types
Test 2: V_{CE} = 350 V dc; I _C = 14 mA dc 2N3439, 2N3439L, 2N3439
Test 3: V _{CE} = 250 V dc; I _C = 20 mA dc 2N3440, 2N3440L, 2N3440

Parameter			Units	Min.	Max.
Breakdown Voltage, Collector-Emitter	I _C = 10 mA, R _{BB1} = 470 Ω, V _{BB1} = 6V, f = 30 to 60 Hz 2N3439, L, UA 2N3440, L, UA	$V_{BR(CEO)}$	V dc	350 250	_

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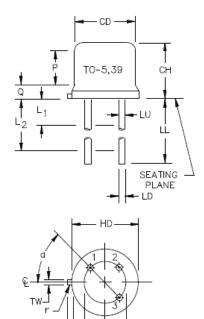
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ΟΝΕΝΤΟ

Outline Drawing (TO-5, TO-39)

	Dimensions				Note	
Symbol	Incl	nes	Millin	Millimeters		
	Min	Max	Min	Max		
CD	.305	.335	7.75	8.51	6	
CH	.240	.260	6.10	6.60		
HD	.335	.370	8.51	9.40		
LC	.200	.200 TP		5.08 TP		
LD	.016	.019	0.41	0.48	8,9	
LL		S	ee note	note 14		
LU	.016	.019	0.41	0.48	8,9	
L ₁		.050		1.27	8,9	
L ₂	.250		6.35		8,9	
P	.100		2.54		7	
Q		.030		0.76	5	
TL	.029	.045	0.74	1.14	3,4	
TW	.028	.034	0.71	0.86	3	
r		.010		0.25	10	
α	45°	TP	45° TP		7	



NOTES:

- Dimensions are in inches.
- 2. Millimeters are given for general information only.
- 3. Beyond r (radius) maximum, TW shall be held for a minimum length of .011 (0.28 mm).
- 4. Dimension TL measured from maximum HD.
- 5. Body contour optional within zone defined by HD, CD, and Q.
- 6. CD shall not vary more than .010 inch (0.25 mm) in zone P. This zone is controlled for automatic handling.
- Leads at gauge plane .054 +.001 -.000 inch (1.37 +0.03 -0.00 mm) below seating plane shall be within .007 inch (0.18 mm) radius of true position (TP) at maximum material condition (MMC) relative to tab at MMC. The device may be measured by direct methods or by gauging procedure.
- Dimension LU applies between L₁ and L₂. Dimension LD applies between L₂ and LL minimum. Diameter is uncontrolled in and beyond LL minimum.
- 9. All three leads.
- 10. The collector shall be internally connected to the case.
- 11. Dimension r (radius) applies to both inside corners of tab.
- 12. In accordance with ASME Y14.5M, diameters are equivalent to Φx symbology.
- 13. Lead 1 = emitter, lead 2 = base, lead 3 = collector.
- For transistor types 2N3439L and 2N3440L (T0-5), dimension LL = 1.5 inches (38.10 mm) min. and 1.75 inches (44.45 mm) max. For transistor types 2N3439 and 2N3440 (T0-39), dimension LL = .5 inch (12.70 mm) min. and .750 inch (19.05 mm) max.

FIGURE 1. Physical dimensions (similar to TO-5 and TO-39).

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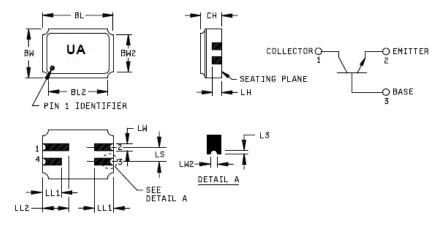
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Outline Drawing (UA Package)



	Dimensions							
	Symbol	Inc	:hes	5	Milli	meters		Note
	-	Min	Ν	/lax	Min	Max	1	
	BL	.215		225	5.46	5.71		
	BL2			225		5.71		
	BW	.145		155	3.68	3.93		
	BW2			155		3.93		
	CH	.061		075	1.55	1.90		3
	L3	.003			0.08			5
	LH	.029		042	0.74	1.07		
	LL1	.032		048	0.81	1.22		
	LL2	.072		088	1.83	2.23		
	LS	.045		055	1.14	1.39		
	LW	.022		028	0.56	0.71		
	LW2	.006		022	0.15	0.56		5
Pin	no.	1			2	3		4

NOTES:

- 1. Dimensions are in inches.
- 2. Millimeters are given for general information only.

Transistor

 Dimension "CH" controls the overall package thickness. When a window lid is used, dimension "CH" must increase by a minimum of .010 inch (0.254 mm) and a maximum of .040 inch (1.020 mm).

Emitter

Base

N/C

- The comer shape (square, notch, radius, etc.) may vary at the manufacturer's option, from that shown on the drawing.
- 5. Dimensions " LW2" minimum and "L3" minimum and the appropriate castellation length define an unobstructed three-dimensional space traversing all of the ceramic layers in which a castellation was designed. (Castellations are required on bottom two layers, optional on top ceramic layer.) Dimension "LW2" maximum define the maximum width and depth of the castellation at any point on its surface. Measurement of these dimensions may be made prior to solder dipping.
- The coplanarity deviation of all terminal contact points, as defined by the device seating plane, shall not exceed .006 inch (0.15mm) for solder dipped leadless chip carriers.
- 7. In accordance with ASME Y14.5M, diameters are equivalent to \$\phix\$ symbology.

Collector

FIGURE 3. Physical dimensions, surface mount (2N3439UA, 2N3440UA) version.

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Temperature-Power Derating Curve

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OMPONENTS

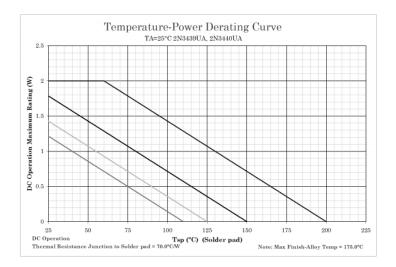
Temperature-Power Derating Curve TA=25°C 2N3439, L, UA, U4, 2N3440, L, UA, U4 0.9 0.8 € Rating Maximum 0.5 0.4 Operation ğ 0.2 0.1 50 75 100 125 150 175 200 225 25 DC Operation Ta (°C) (Ambient) Thermal Resistance Junction to Ambient = 175°C/W Note: Max Finish-Alloy Temp = 175.0°C

NOTES:

1. All devices are capable of operating at ≤ T_J specified on this curve. Any parallel line to this curve will intersect the appropriate power for the desired maximum T_J allowed.

- 2. Derate design curve constrained by the maximum junction temperature ($T_J \le 200^\circ$ C) and power rating specified. (See 1.3 herein.)
- Derate design curve chosen at T_J ≤ 150°C, where the maximum temperature of electrical test is performed. 4. Derate design curves chosen at T_J ≤, 125°C, and 110°C to show power rating where most users want to limit T_J
 - in their application.

FIGURE 6. Temperature-power derating for all types RoJA (TO-5, TO-39, UA, and U4).



NOTES:

- 1. All devices are capable of operating at \leq T_J specified on this curve. Any parallel line to this curve will intersect the appropriate power for the desired maximum T_{.1} allowed.
- 2. Derate design curve constrained by the maximum junction temperature (T_J ≤ 200°C) and power rating specified. (See 1.3 herein.) Derate design curve chosen at T₁ ≤ 150°C, where the maximum temperature of electrical test is performed.
- 4. Derate design curves chosen at $T_J \le 125^{\circ}$ C, and 110° C to show power rating where most users want to limit T_J in their application.

FIGURE 7. Temperature-power derating for 2N3439UA and 2N3440UA



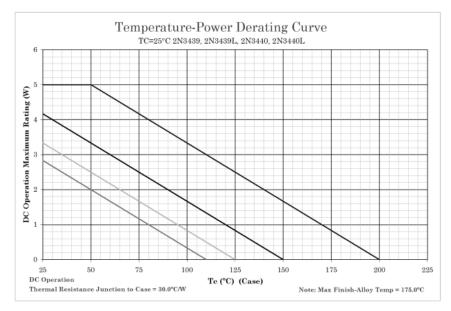
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Temperature-Power Derating Curve



NOTES:

- All devices are capable of operating at ≤ T_J specified on this curve. Any parallel line to this curve will intersect the appropriate power for the desired maximum T_J allowed.
- 2. Derate design curve constrained by the maximum junction temperature ($T_J \le 200^{\circ}C$) and power rating specified. (See 1.3 herein.)
- 3. Derate design curve chosen at $T_J \le 150^{\circ}$ C, where the maximum temperature of electrical test is performed.
- 4. Derate design curves chosen at $T_J \le 125^{\circ}$ C, and 110° C to show power rating where most users want to limit T_J in their application.

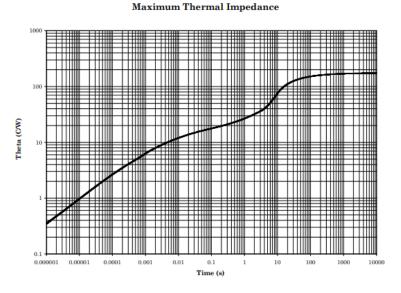
FIGURE 9. Temperature-power derating for 2N3439, 2N3439L, 2N3440, and 2N3440L.

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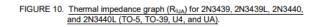


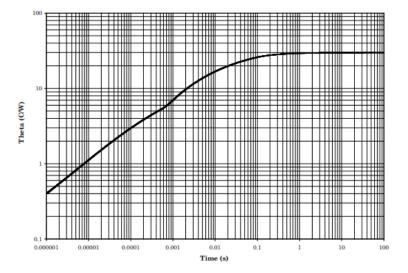
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Thermal Impedance Curves



 T_{A} = +25°C, P_{T} = 0.8W, thermal resistance $R_{\theta JA}$ = 175°C/W.





Maximum Thermal Impedance

T_C = +25°C, P_T = 5.0W, thermal resistance R_{BJC} = 30°C/W, steel.

FIGURE 11. Thermal impedance graph (R_{BUC}) for 2N3439, 2N3439L, 2N3440, and 2N3440L (TO-5 and TO-39).

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Thermal Impedance Curves

100 10 Theta (CW) -----1 ∰ 111 0.1 0.000001 0.00001 0.0001 0.001 0.01 0.1 10 Time (s)

Maximum Thermal Impedance

Tc = +25°C, thermal resistance Rause = 70°C/W, Pdiss = 2W.

FIGURE 12. Thermal impedance graph (Reuse) for 2N3439UA and 2N3440UA.

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